WHAT IS CLAIMED IS:

1. A chip device comprising:

a. a leadframe comprising a plurality of leads;

b. a first die coupled to a first side of the leadframe with solder;

c. a second die coupled to a second side of the leadframe with solder; and

d. a molded body surrounding at least a portion of the leadframe and the dies.

2. The chip device of claim 1 wherein at least one of the dies is a bumped die.

3. The chip device of claim 2 wherein both dies are bumped dies.

4. The chip device of claim 1 wherein the first die is a MOSFET.

5. The chip device of claim 4 wherein the second die is a controller IC.

6. The chip device of claim 1 wherein a drain region of the first die is exposed through the molded body.

7. A method of making a chip device, the method comprising:

providing a leadframe comprising a plurality of leads;

placing a first die on a first side of the leadframe with first solder therebetween;

reflowing the first solder at a first temperature;

flipping the leadframe;

placing a second die on a second side of the leadframe with second solder therebetween; and

reflowing the second solder at a second temperature lower than the first temperature.

8. A method of making a chip device, the method comprising:

providing a leadframe comprising a plurality of leads;

flipping a first die on a first side of the leadframe with first solder therebetween;

reflowing the first solder at a first temperature;

flipping the leadframe;

flipping a second die on a second side of the leadframe with second solder therebetween;

reflowing the second solder at a second temperature lower than the first temperature; and

placing a molded body around at least a portion of the leadframe and the dies.